

## C1206C225M3RECTU

Aliases (C1206C225M3REC7800)

ESD SMD Comm X7R, Ceramic, 2.2 uF, 20%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 1206



Click [here](#) for the 3D model.

General Information	
Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	41 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.6mm +/-0.20mm
B	0.5mm +/-0.25mm

Specifications	
Capacitance	2.2 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000

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